ABSTRACT

AN EMBEDDED ELECTRONIC DEVICE AND METHOD FOR MANUFACTURING AN EMBEDDED ELECTRONIC DEVICE

An embedded electronic device and a method for manufacturing the same wherein the embedded electronic device is composed of a printed circuit board, having a top surface and a bottom surface, a plurality of circuit components attached to the top surface of the printed circuit board having a plurality of standoffs on the bottom surface of the printed circuit board, a bottom overlay attached to the bottom surface of the printed circuit board, a top overlay positioned above the top surface of the printed circuit board and a core layer positioned between the top surface of the printed circuit board and the top overlay.

Figure 1